## **DB4X314F**

## Silicon epitaxial planar type

For high speed switching circuits

#### ■ Features

- Short reverse recovery time t<sub>rr</sub>
- ullet Small reverse current  $I_R$
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

#### ■ Marking Symbol: 5C

#### ■ Basic Part Number

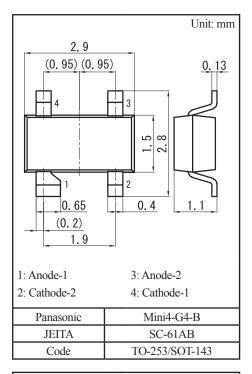
Dual DB2J314 (Parrarel, oppositely arranged)

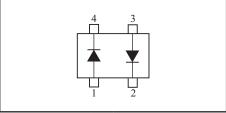
## ■ Packaging

DB4X314F0R Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter                     | Symbol           | Rating           | Unit       |    |  |
|-------------------------------|------------------|------------------|------------|----|--|
| Reverse voltage               |                  | V <sub>R</sub>   | 30         | V  |  |
| Maximum peak reverse voltage  |                  | V <sub>RM</sub>  | 30         | V  |  |
| Forward current               | Single           | 1                | 30         | mA |  |
|                               | Series           | $ I_{\rm F}$     | 20         |    |  |
| Peak forward current          | Single           | ,                | 150        | mA |  |
|                               | Series           | $ I_{FM}$        | 110        |    |  |
| Junction temperature          |                  | T <sub>j</sub>   | 125        | °C |  |
| Operating ambient temperature |                  | T <sub>opr</sub> | -40 to +85 | °C |  |
| Storage temperature           | T <sub>stg</sub> | -55 to +125      | °C         |    |  |



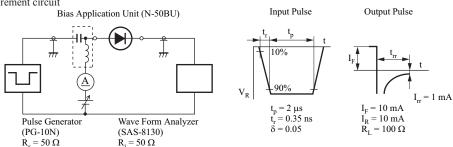


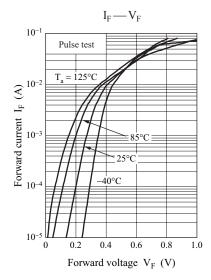
### ■ Electrical Characteristics $T_a = 25$ °C±3°C

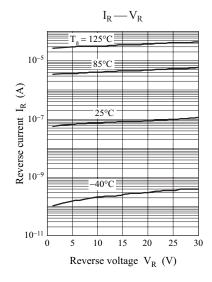
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|--------------------------|-----------------|--|-----|-----|-----|------|--|
| Parameter                | Symbol          | Conditions   | Min | Тур | Max | Unit |  |
| Forward voltage          | V <sub>F1</sub> | $I_F = 1 \text{ mA}$   |     |     | 0.4 | V    |  |
|                          | $V_{F2}$        | $I_F = 30 \text{ mA}$  |     |     | 1.0 |      |  |
| Reverse current          | $I_R$           | $V_R = 30 \text{ V}$   |     |     | 300 | nA   |  |
| Terminal capacitance     | C <sub>t</sub>  | $V_R = 10 \text{ V}, f = 1 \text{ MHz}$                              |     | 1.5 |     | pF   |  |
| Reverse recovery time *1 | t <sub>rr</sub> | $I_F = I_R = 10 \text{ mA}, I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$ |     | 1.0 |     | ns   |  |

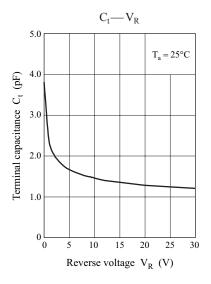
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 2 GHz
- 4. \*1: t<sub>rr</sub> measurement circuit





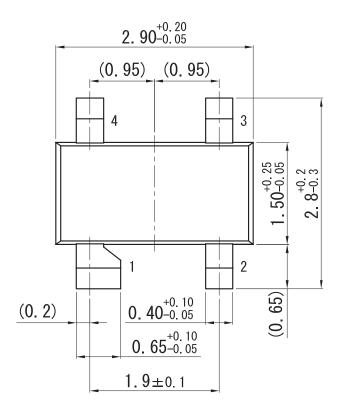


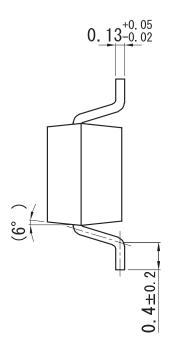


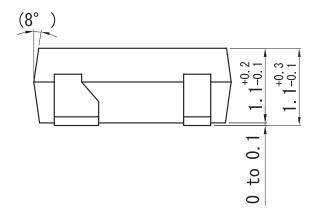
Ver. CED 2

Mini4-G4-B

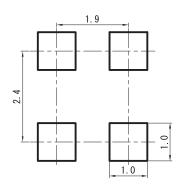
Unit: mm







### ■ Land Pattern (Reference) (Unit: mm)



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